IAB PROJECT ABSTRACT/DESCRIPTION FORM

INVESTIGATORS: David N. Ruzic

PROJECT TITLE: Plasma Engineering at the University of Illinios' Center for Plasma Material Interactions

ABSTRACT/DESCRIPTION:
The Center for Plasma Material Interactions at the University of Illinois, Urbana-Champaign, focuses on making the machines that make microelectronics. Current projects include EUV source and collector development for 32nm-node lithography, advanced all-ionized-metal PVD for copper seed, high-aspect-ratio etching for high density memory, and particle removal techniques for pellicle-less reticule handling. Support for these projects total more than one million dollars per year and comes from INTEL, Novellus, Micron, Ushio (Japan), ASML (Netherlands), Xtreme Technologies (Germany), CYMER, and Starfire Industries. Fusion technology is also supported by the US DOE. In this talk Prof. Ruzic will give an overview of the Center's work and show its interconnections.

PROGRESS TO DATE: N/A

BENEFITS TO MEMBERS (Achieved and Anticipated) N/A

MILESTONES:: N/A